

FORM PTO-1449
(Rev. 2-32)U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY DOCKET NO.
560043620578CONTINUATION IN PART
APPLICATION OF
SERIAL NO.:
10/048,871INFORMATION DISCLOSURE
STATEMENT BY APPLICANT

(Use several sheets if necessary)

APPLICANT: Michael R. Cosley and Richard L. Fischer

FILING DATE:
Filed Concurrently Herewith

GROUP:

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER								DATE	NAME	CLASS	SUB- CLASS	FILING DATE IF APPROPRIATE
TD	2003/	0	0	1	0	0	5	0		1/16/2003	Alexander Robin Scott			
TD		4	1	5	1	5	4	8		02/24/79	Klein et al.			
TD		6	0	3	9	1	1	4		03/21/2000	Becker et al.			
TD		5	7	6	9	1	5	4		06/23/98	Adkins et al.			
TD		5	1	7	9	5	0	0		01/12/93	Koubek et al.			
TD		5	2	2	0	8	0	9		06/22/93	Mark G. Voss			
TD		3	3	6	1	1	9	5		01/02/68	Meyerhoff et al.			
TD		5	1	5	9	5	2	9		10/27/92	Lovgren et al.			
TD		4	5	6	1	0	4	0		12/24/85	Eastman et al.			
TD		4	6	1	2	9	7	8		09/23/86	John M. Cutchaw			
TD		4	8	6	6	5	7	0		09/12/89	Warren W. Porter			
TD		5	3	1	6	0	7	5		05/31/94	Quon et al.			
TD		4	6	8	5	5	1	2		08/11/87	Edelstein et al.			
TD		5	5	8	7	8	8	0		12/24/96	Phillips et al.			
TD		5	0	0	5	6	4	0		04/09/91	Lapinski et al.			
TD		4	9	4	0	0	8	5		07/10/90	Nelson et al.			

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER								DATE	COUNTRY	CLASS	SUBCL ASS	TRANSLATION	
	WO	84/02177								06/07/84	World			YES	NO
															X

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

TD		Little, William, March 1978, IBM Corp., Vol. 20 No. 10, page 3919												
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EXAMINER

DATE CONSIDERED

11/09/06

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

(Form PTO-1449 [6-4])

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TD		5	5	4	4	6	9	6		8/13/96	John E. Leland			
TD		5	6	9	6	4	0	5		12/9/97	John David Weld			
TD		5	8	2	3	0	0	5		10/20/98	Alexander et al.			
TD		5	8	7	0	8	2	3		2/16/99	Bezama et al.			

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		DOCUMENT NUMBER								DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
														YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

TD			"An Electrodynamics Polarization Micropump for Electronic Cooling"; J. Darabi and D. DeVoe; Journal of Microelectromechanical Systems, Vol. 10, No. 1, pgs. 98-106, March 2001											
TD			"Heat Transfer from Micro-Finned and Flat Surfaces to Flow of Fluorinert Coolant; Boiling Heat Transfer"; Mizunuma et al.; 1998 InterSociety Conference on Thermal Phenomena, pgs. 386-391, August 1998											
TD			"Immersion Cooling of Electronics in Fluidized Beds of Dielectric Particles"; Robert C. Brown and Scott S. Jasper; Heat Transfer Engineering, Vol. 10, No. 3 pgs. 36-42, 1989											
TD			"Optimal Structure for Microgrooved Cooling Fin for High-Power LSI Devices"; S. Sasaki and T. Kishimoto; Electronics & Mechanics Technology Laboratories, October 21, 1986											
TD			"Gas Cooling Enhancement Technology for Integrated Circuit Chips"; Kishimoto et al.; IEEE Transactions of Components, Hybrids, and Manufacturing Technology, Vol. CHMT-7, No. 3, pgs. 286-293, September 1984											
TD			"The Effect of Tip Convection on the Performance and Optimum Dimensions of Cooling Fins"; K. Laor and H. Kalman; Int. Comm. Heat mass. Transfer, Vol. 19, pp. 569-584, 1992											

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TD	4 3 9 2 3 6 2	7/12/83	William A. Little			
TD	4 4 9 8 1 1 8	2/5/85	David L. Bell			
TD	4 9 4 1 5 3 0	7/17/90	Lawrence E. Crowe			
TD	5 0 6 7 0 4 7	11/19/91	Kaveh Azar			
TD	5 0 8 8 0 0 5	2/11/92	Michael P. Ciaccio			
TD	5 0 9 9 3 1 1	3/24/92	Bonde et al.			
TD	5 0 9 9 9 1 0	3/31/92	Walpole et al.			
TD	5 1 6 9 3 7 2	12/8/92	Armand Tecco			
TD	5 1 8 3 1 0 4	2/2/93	Shiomo D. Novotay			
TD	5 2 1 8 5 1 5	6/8/93	Anthony F. Bernhardt			
TD	5 2 8 5 3 4 7	2/8/94	Fox et al.			
TD	5 3 6 5 7 4 9	11/22/94	Warren W. Porter			
TD	5 3 9 4 9 3 6	3/7/95	Gerald A. Budelman			
TD	5 5 0 9 4 6 8	4/23/96	Roger Lopez			

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DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION
					YES NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

TD		"Pool Boiling Heat Transfer From Plain and Microporous, Square Pin-Finned Surfaces in Saturated FC-72"; K.N. Rainey and S.M. You; Journal of Heat Transfer, Vol 122, pgs. 509-516, August 2000
TD		"Effects of Perpendicular Flow Entry on Convective Heat/Mass Transfer From Pin-Fin Arrays"; Chyu et al.; Journal of Heat Transfer; Vol 121, Pgs. 668-674, August 1999
TD		"Pool Boiling Heat Transfer With an Array of Flush-Mounted, Square Heaters on a Vertical Surface"; S.M. You et al; Journal of Electronic Packaging; Vol. 119, Pgs. 17-24, March 1997
TD		"Combined Pressure and Subcooling Effects on Pool Boiling From a PPGA Chip Package"; A.A. Watwe et al; Journal of Electronic Packaging, Vol. 199, pgs. 95-105, June 1997
TD		"Analytic Modeling, Optimization, and Realization of Cooling Devices in Silicon Technology"; Perret et al.; IEEE Transactions on Components and Packaging Technologies, Vol. 23, No. 4, Pgs. 665-671, December 2000

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11/09/06